Product Change Notification

Change Notification #: **119414-00**

Change Title: **Select Hot Swap Backplane SKUs,
PCN 119414-00, Product Material,
New Alternate Hot Swap Backplanes**

Date of Publication: **January 13, 2023**

Key Characteristics of the Change:

Product Material

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material*	February 15, 2023

* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

Due to Integrated Circuit (IC) shortage from the supplier, the Programmable System-On-Chip (PSOC) used on the Hot Swap Backplanes will be replaced with an alternative component. The new component is identical in function to previous one but differs slightly in form factor.

For business continuity, demand fulfillment, and to minimize customer impact, an interposer PCB supporting the new component was used. The new component has passed all functional and electrical validation test successfully.

Customer Impact of Change and Recommended Action:

Intel anticipates no impact to customers. Please contact your local Intel Field Sales Representative if you have any further questions about these changes.

Products Affected/Intel Ordering Codes:

Marketing Name	Product Code	MM#	Pre Change TA	Pre Change PBA	Post Change TA	Post Change PBA
Hot-swap 8x2.5inch SAS/NVMeCombo Drive Bay Kit	A2U8X25S3PHS	955858	J12659-009	H88386-252 H88386-253 H88386-311 H88386-301	J12659-010	H88386-252 H88386-253 H88386-311 H88386-301 H88386-401
1U 8x2.5 inch SAS/NVMe Hot Swap Backplane	F1U8X25S3PHS	955868	J11107-009	H88382-351 H88382-352 H88382-411 H88382-401	J11107-010	H88382-351 H88382-352 H88382-411 H88382-401 H88382-501
2U 12x3.5inch SAS and 2x NVMe Hot Swap Backplane	F2U12X35S3PH	955869	J10383-007	H88392-351 H88392-411 H88392-401	J10383-008	H88392-351 H88392-411 H88392-401 H88392-501
2U 8x2.5 inch SAS/NVMe Hot Swap Backplane	F2U8X25S3PHS	955870	H97230-007	H88386-252 H88386-253 H88386-301	H97230-008	H88386-252 H88386-253 H88386-301 H88386-401

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
January 13, 2023	00	Originally Published PCN

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No response from customers will be deemed an acceptance of the change, and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below.

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